

Amendment to the Specification

The paragraph on page 12, line 19 to page 13, line 2 has been amended as follow:

--Moreover, a global interconnection layers 504, having metals layers, plugs and inter-metal dielectric layers, is above the global interconnection layer. A metal layer is formed on the global interconnection layer 504, and is defined as external electrical electrode pads 508, which are covered by an protective level 509 for protection. The electrode pads 508 are typically formed with multiple layers including a buried metal layer and may be interposed with metallizations, such as Under-bump Metallurgy (UBM), or solder bumps, generally above the electrode pads 508. --